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Shi

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(54) **ELECTROSTATIC CHUCK FOR SEMICONDUCTOR MANUFACTURE**

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(51) **LOC (14) Cl.** **13-03**
(52) **U.S. Cl.**
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(58) **Field of Classification Search**
USPC D13/182; D15/140
CPC H01L 21/67098; H01L 21/67109; H01L 21/683; H01L 21/6831; H01L 21/6833; H01L 21/6835; H01L 21/68; H01L 21/67; B23Q 3/15; B23Q 3/154; B23Q 3/1543; B23Q 3/1546; B23B 2270/38; B23B 31/28; G03F 7/70708; G03F 7/707; H02N 13/00; H02N 15/00
See application file for complete search history.

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(Continued)

Primary Examiner — Elizabeth J Oswecki

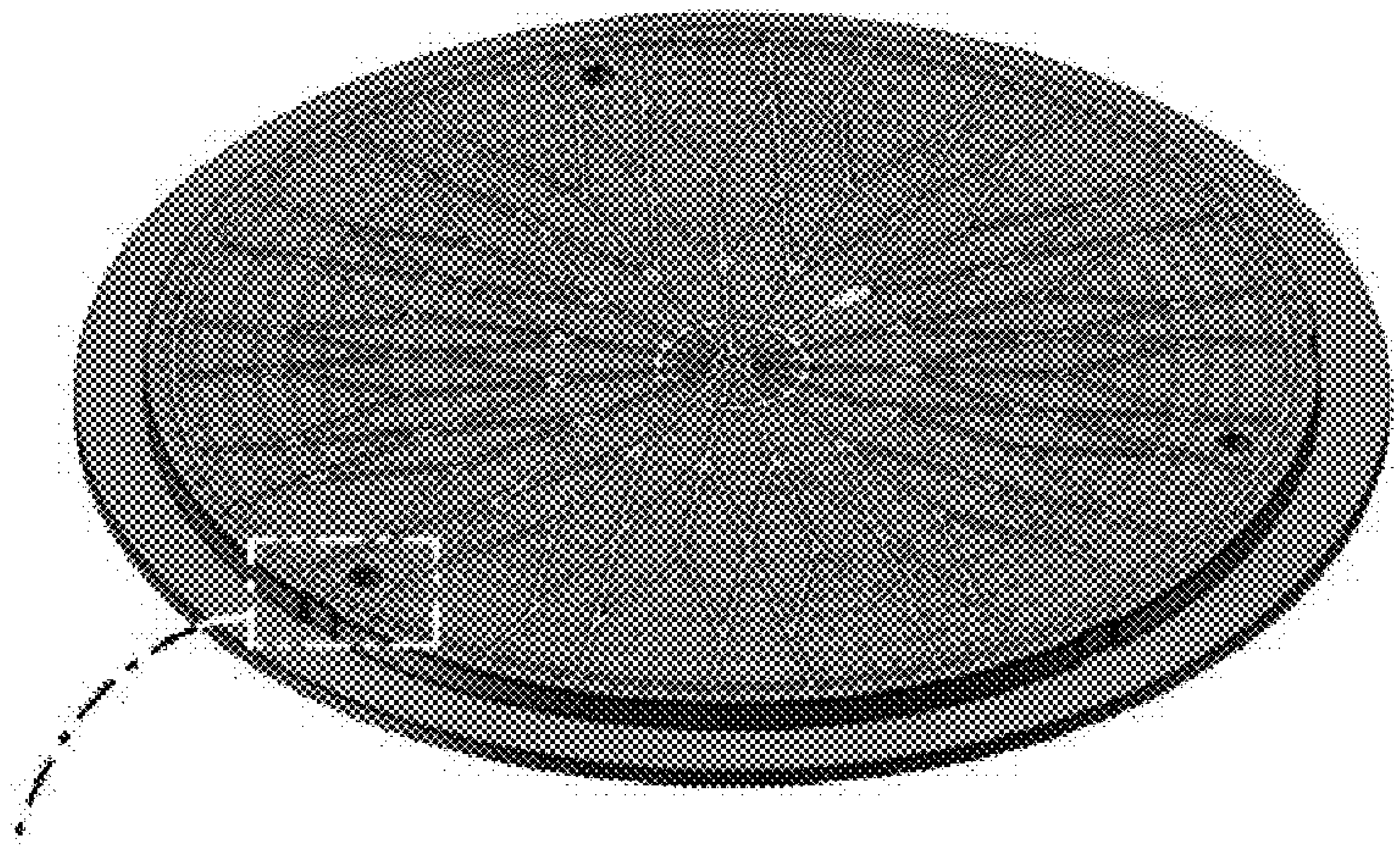
(57) **CLAIM**

The ornamental design for an electrostatic chuck semi conductor manufacture, as shown and described.

DESCRIPTION

1. Electrostatic chuck for semiconductor manufacture
FIG. **1.1** is a front perspective view of an electrostatic chuck for semiconductor manufacture showing my new design;
FIG. **1.2** is another front perspective view thereof;
FIG. **1.3** is a front elevation view thereof;
FIG. **1.4** is a top plan view thereof;
FIG. **1.5** is a bottom plan view thereof;
FIG. **1.6** is a left side elevation view thereof;
FIG. **1.7** is a right side elevation view thereof;
FIG. **1.8** is an enlarged portion view labeled, “Fig. **1.8**” in Fig. **1.1**; and
FIG. **1.9** is an enlarged portion view labeled, “Fig. **1.9**” in Fig. **1.2**.
The dashed-dot lines in Figs. **1.1**, **1.2**,**1.8** and **1.9** denote the boundaries of the enlarged portion views shown in Figs. **1.8** and **1.9** and form no part of the claimed design.

1 Claim, 9 Drawing Sheets



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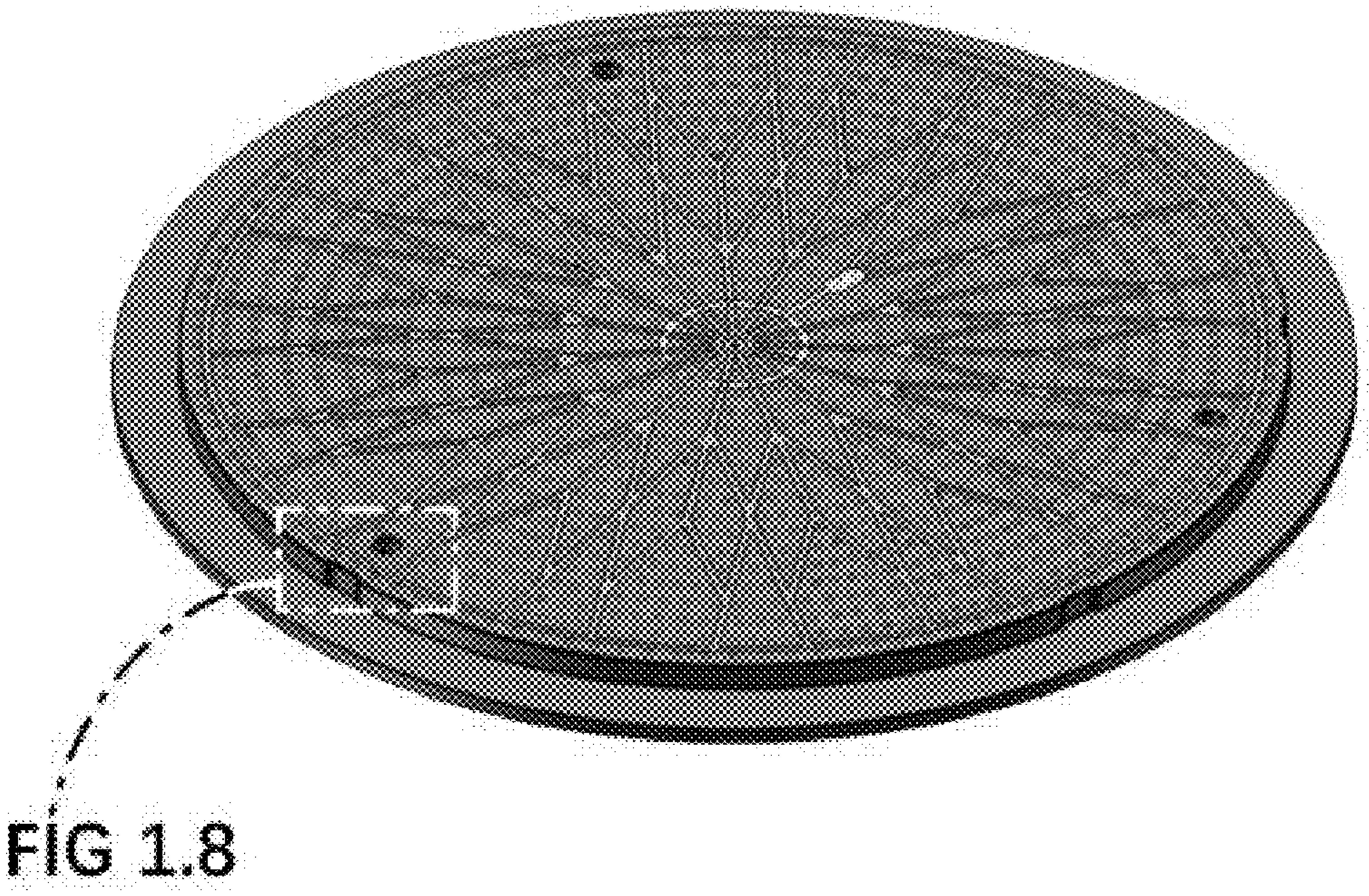

FIG 1.1

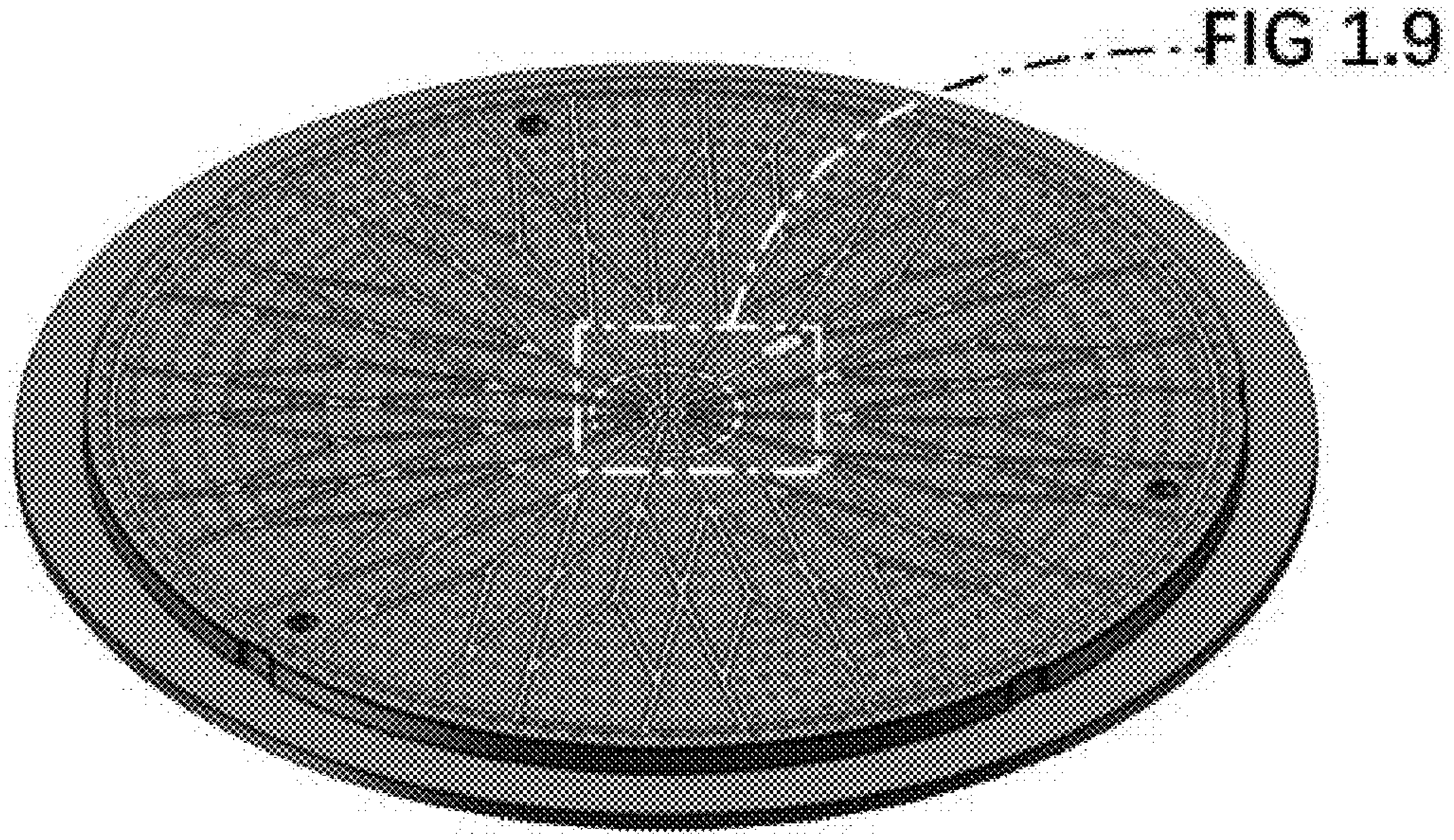

FIG 1.2

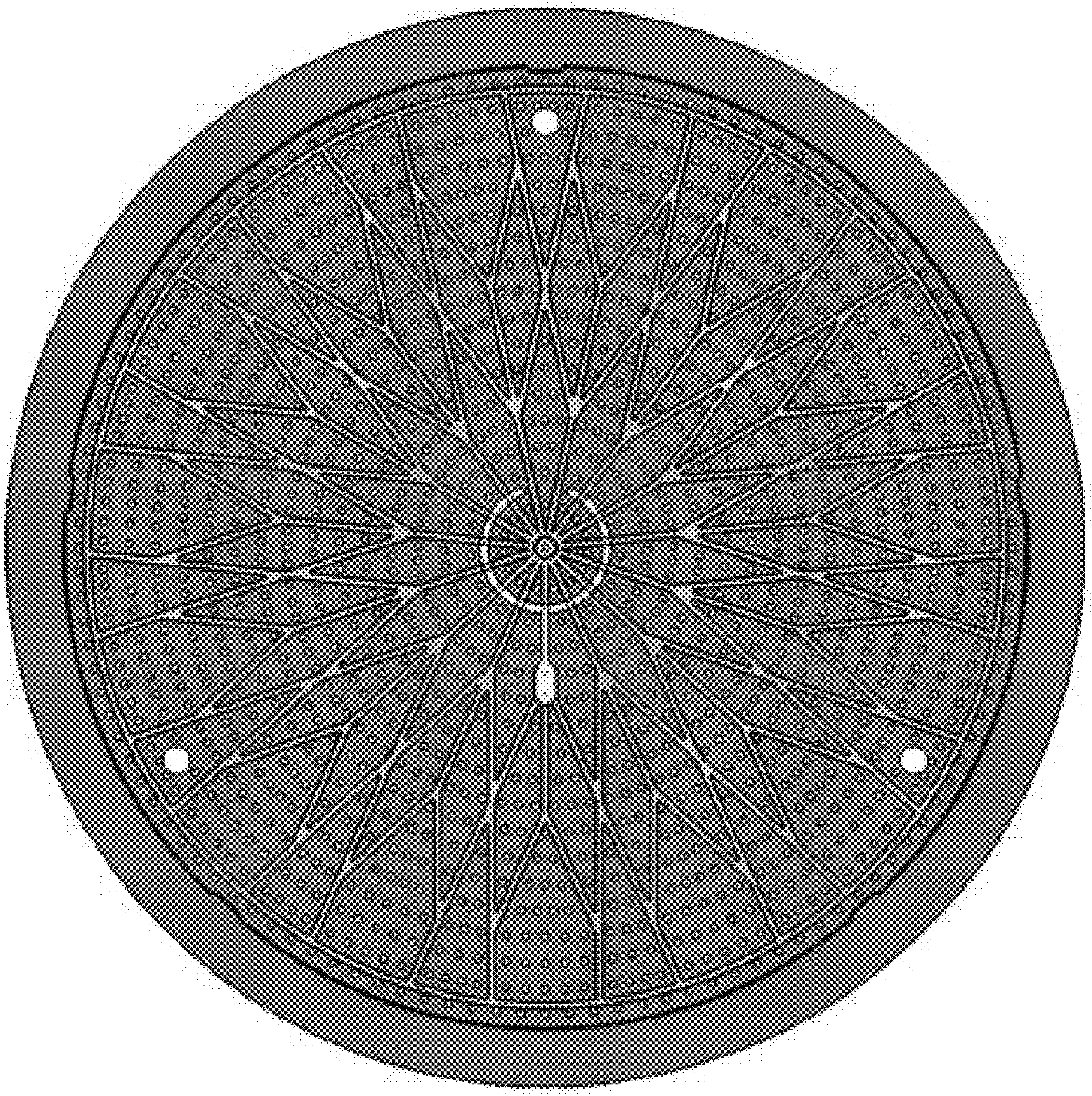

FIG. 1.3

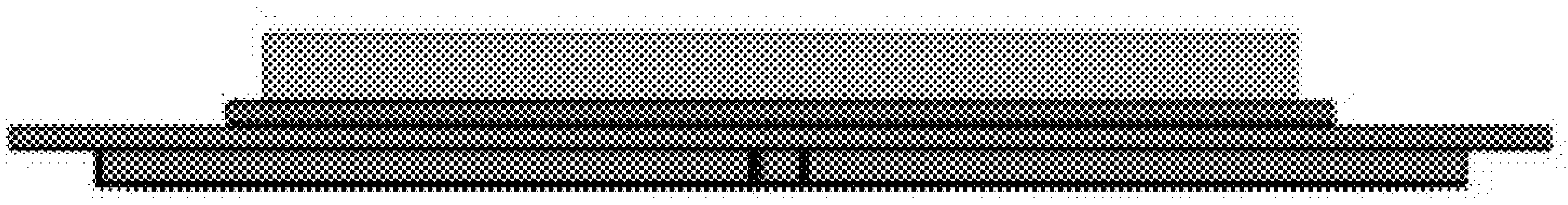

FIG. 1.4

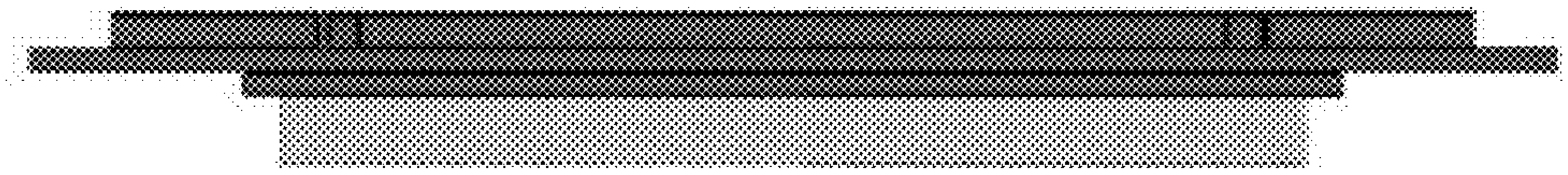

FIG. 1.5

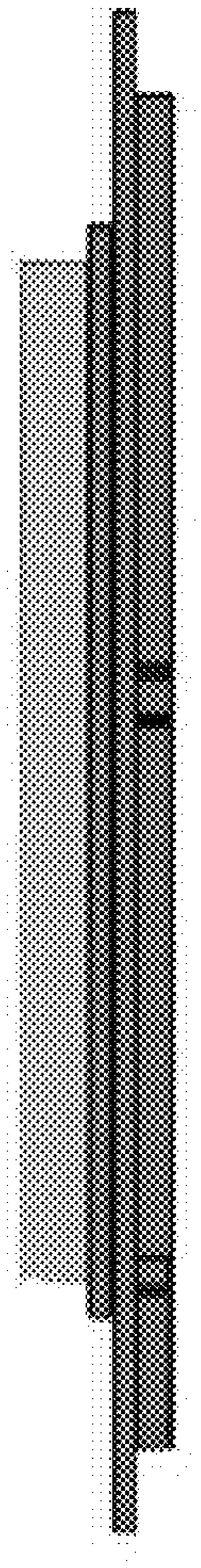

FIG. 1.6

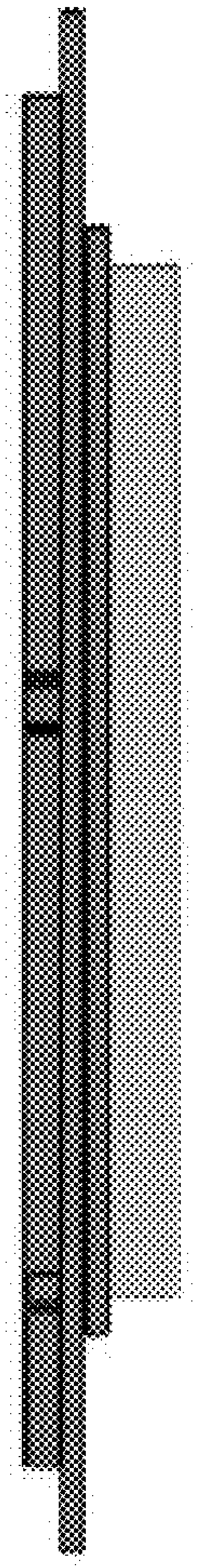

FIG 1.7

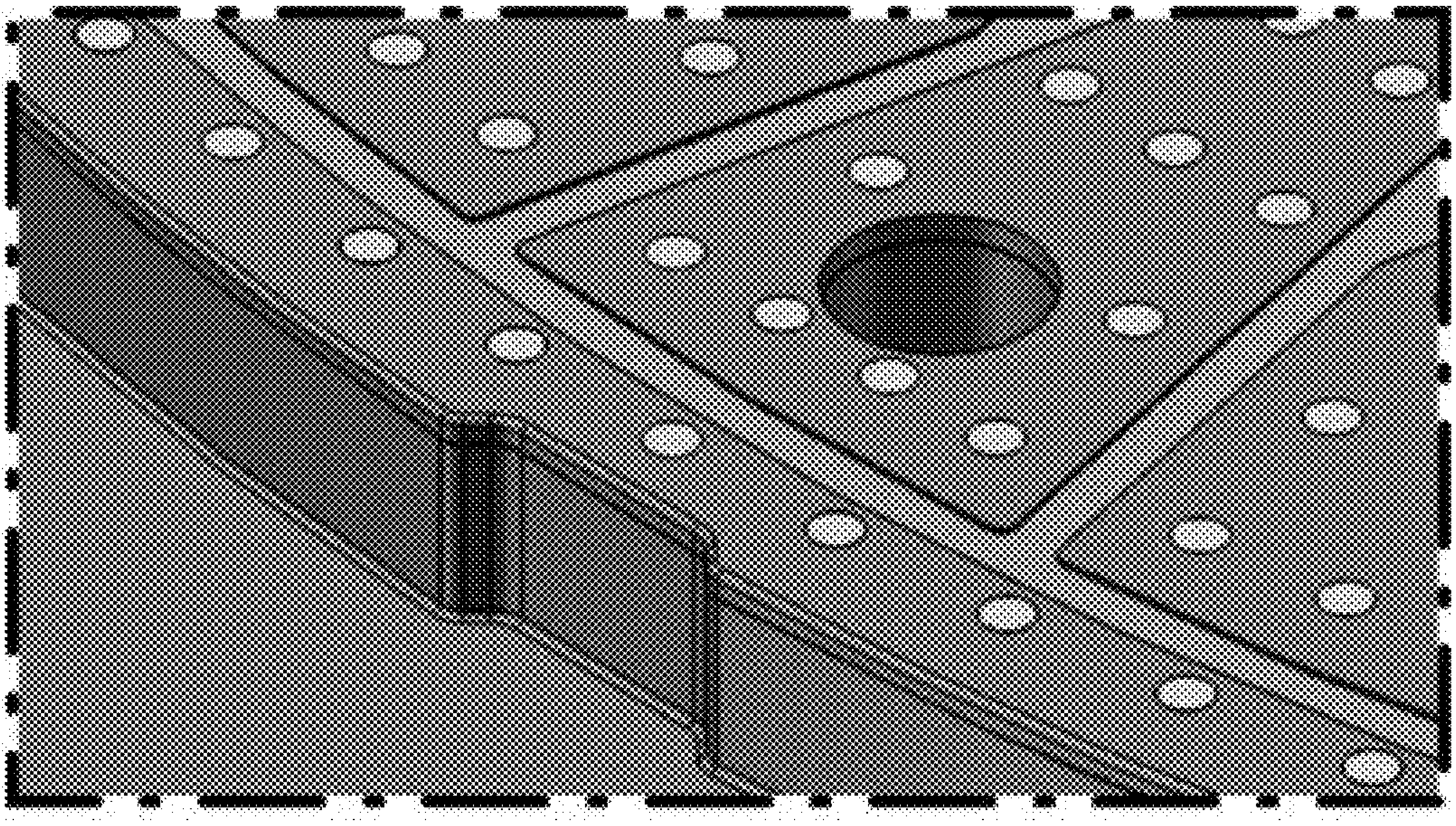

FIG 1.8

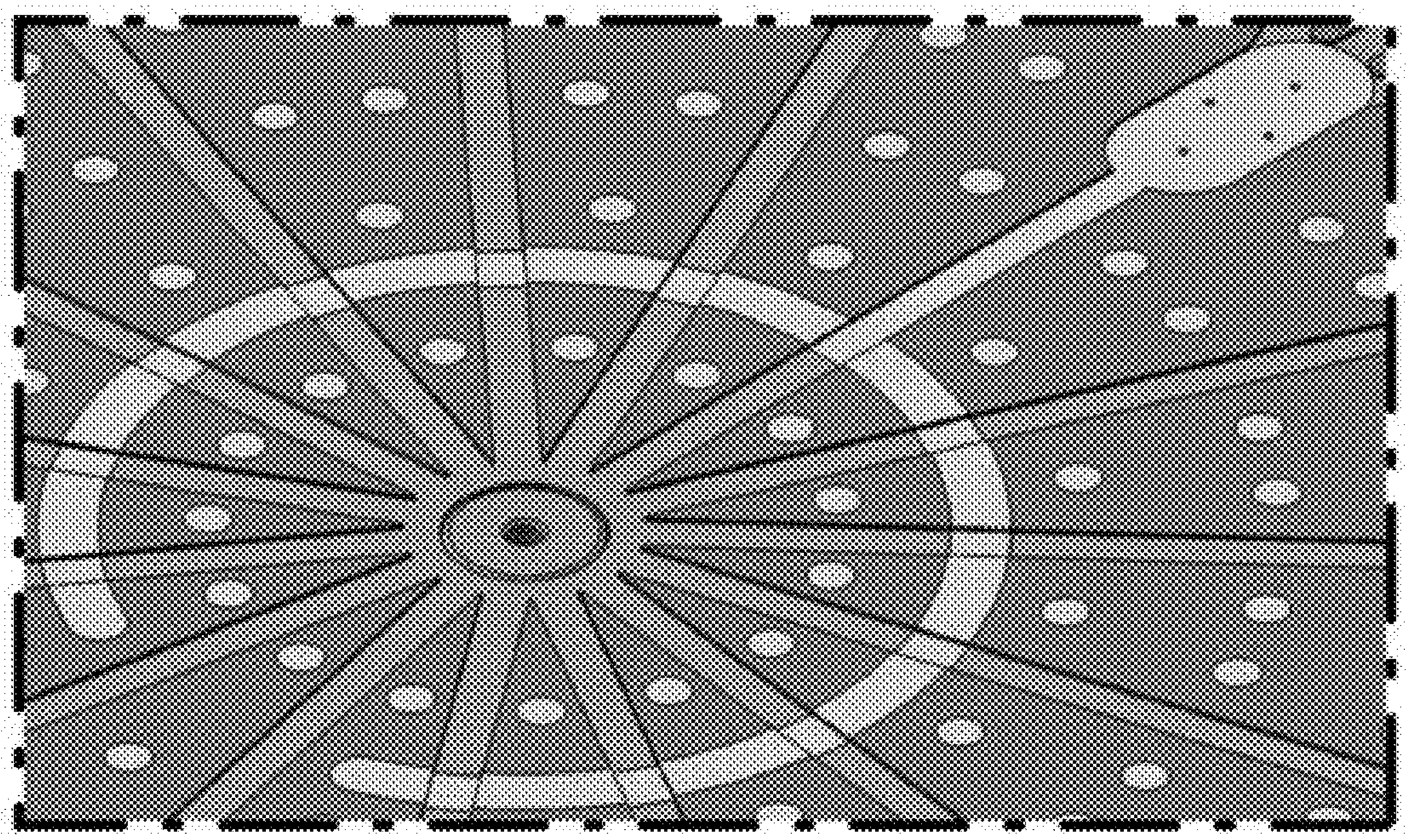

FIG. 1.9